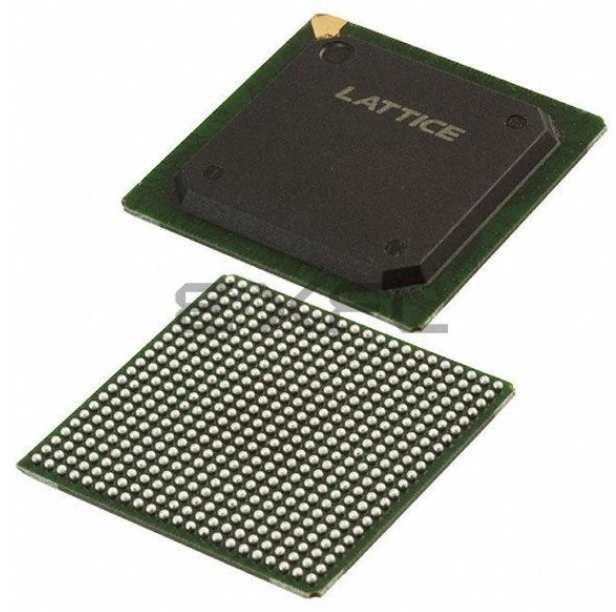
Lattice Semiconductor Corporation - LC5512MV-45FN484C Datasheet



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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	4.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	512
Number of Gates	-
Number of I/O	253
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc5512mv-45fn484c

Product Line	Ordering Part Number	Product Status	Reference PCN
LC51024MV	LC51024MV-52F484C	Active / Orderable	
	LC51024MV-52FN484C		
	LC51024MV-75F484C		
	LC51024MV-75FN484C		
	LC51024MV-75F484I		
	LC51024MV-75FN484I		
	LC51024MV-52F672C		
	LC51024MV-52FN672C		
	LC51024MV-75F672C		
	LC51024MV-75FN672C		
	LC51024MV-75F672I		
	LC51024MV-75FN672I		
LC51024MB	LC51024MB-52F484C	**Discontinued**	PCN#09-10
	LC51024MB-52FN484C		
	LC51024MB-75F484C		
	LC51024MB-75FN484C		
	LC51024MB-75F484I		
	LC51024MB-75FN484I		
	LC51024MB-52F672C		
	LC51024MB-52FN672C		
	LC51024MB-75F672C		
	LC51024MB-75FN672C		
	LC51024MB-75F672I		
	LC51024MB-75FN672I		
LC51024MC	LC51024MC-52F484C	**Discontinued**	PCN#09-10
	LC51024MC-52FN484C		
	LC51024MC-75F484C		
	LC51024MC-75FN484C		
	LC51024MC-75F484I		
	LC51024MC-75FN484I		
	LC51024MC-52F672C		
	LC51024MC-52FN672C		
	LC51024MC-75F672C		
	LC51024MC-75FN672C		
	LC51024MC-75F672I		
	LC51024MC-75FN672I		

5000MX. Incoming signals may connect to the global routing pool or the registers in the MFBs. An Output Sharing Array (OSA) increases the number of I/O available to each MFB, allowing a complete function high-performance access to the I/O. There are four clock pins that drive four global clock nets within the device. Two sysCLOCK PLLs are provided to allow the synthesis of new clocks and control of clock skews.

Multi-Function Block (MFB)

Each MFB in the ispXPLD 5000MX architecture can be configured in one of the six following modes. This provides a flexible approach to implementing logic and memory that allows the designer to achieve the mix of functions that are required for a particular design, maximizing resource utilization. The six modes supported by the MFB are:

- SuperWIDE Logic Mode
- True Dual-port SRAM Mode
- Pseudo Dual-port SRAM Mode
- Single-port SRAM Mode
- FIFO Mode
- Ternary CAM Mode

The MFB consists of a multi-function array and associated routing. Depending on the chosen functions the multi-function array uses up to 68 inputs from the GRP and the four global clock and reset signals. The array outputs data along with certain control functions to the macrocells. Output signals can be routed internally for use elsewhere in the device and to the sysIO banks for output. Figure 2 shows the block diagram of the MFB. The various configurations are described in more detail in the following sections.

Figure 2. MFB Block Diagram

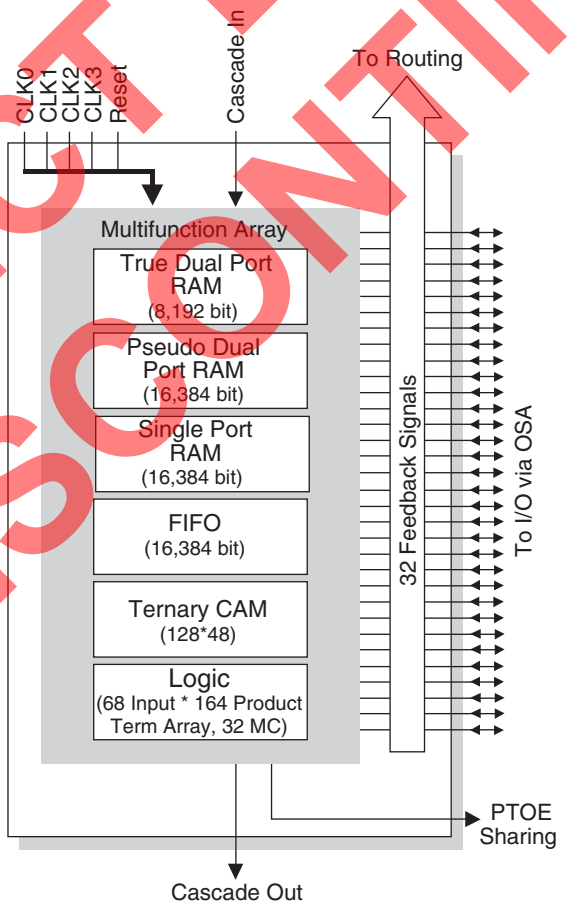
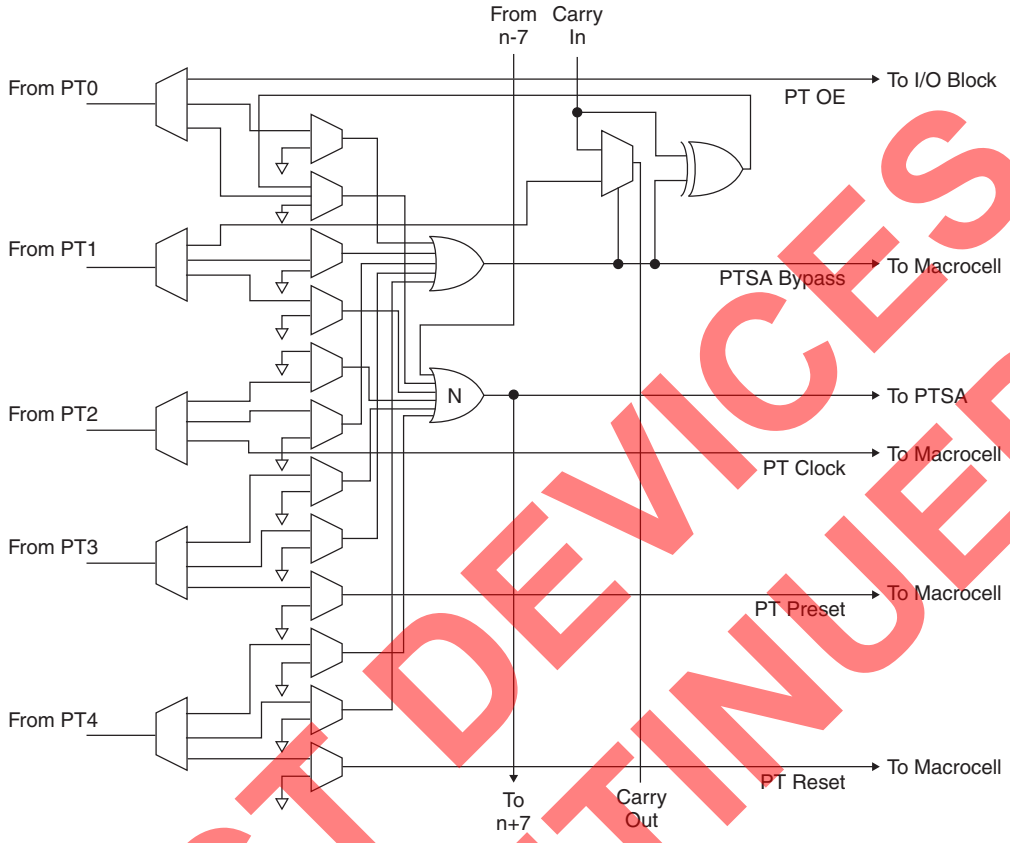


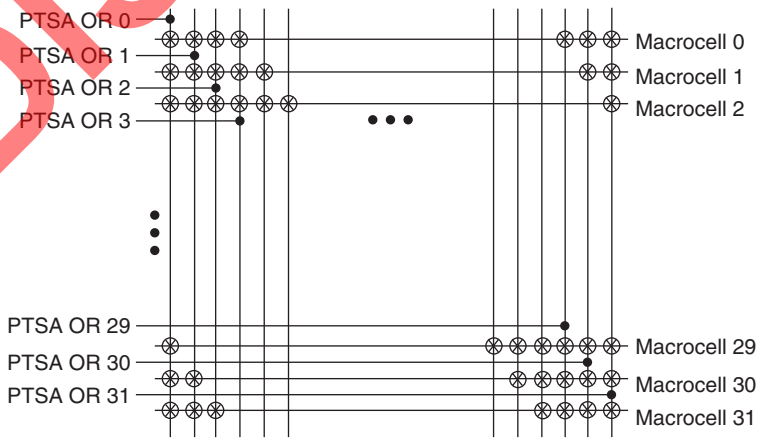
Figure 6. Dual-OR PT Sharing Array



Product Term Sharing Array

The Product Term Sharing Array (PTSA) consists of 32 inputs from the Dual-OR Array (Expandable PTSA OR) and 32 outputs directly to the macrocells. Each output is the OR term of any combination of the seven Expandable PTSA OR terms connected to that output. Every Nth macrocell is connected to N-3, N-2, N-1, N, N+1, N+2 and N+3 PTSA OR terms via a programmable connection. This wraps around the logic, for example, Macrocell 0 gets its logic from 29, 30, 31, 0, 1, 2, 3. The Expandable PTSA OR used in conjunction with the PTSA allows wide functions to be implemented easily and efficiently. Without using the Expandable PTSA OR capability, the greatest number of product terms that can be included in a single function with one pass of delay is 35. Up to 160 product terms can be included in a single function through the use of the expandable PTSA OR capability. Figure 7 shows the graphical representation of the PTSA.

Figure 7. Product Term Sharing Array (PTSA)



Pseudo Dual-Port SRAM Mode

In Pseudo Dual-Port SRAM Mode the multi-function array is configured as a SRAM with an independent read and write ports that access the same 16,384-bits of memory. Data widths of 1, 2, 4, 8, 16 and 32 are supported by the MFB. Figure 10 shows the block diagram of the Pseudo Dual-Port SRAM.

Write data, write address, chip select and write enable signals are always synchronous (registered). The read data and read address signals can be synchronous or asynchronous. Reset is asynchronous. All write signals share the same clock, and clock enable. All read signals share the same clock and clock enable. Reset is shared by both read and write signals. Table 6 shows the possible sources for the clock, clock enable and initialization signals for the various registers.

Figure 10. Pseudo Dual-Port SRAM Block Diagram

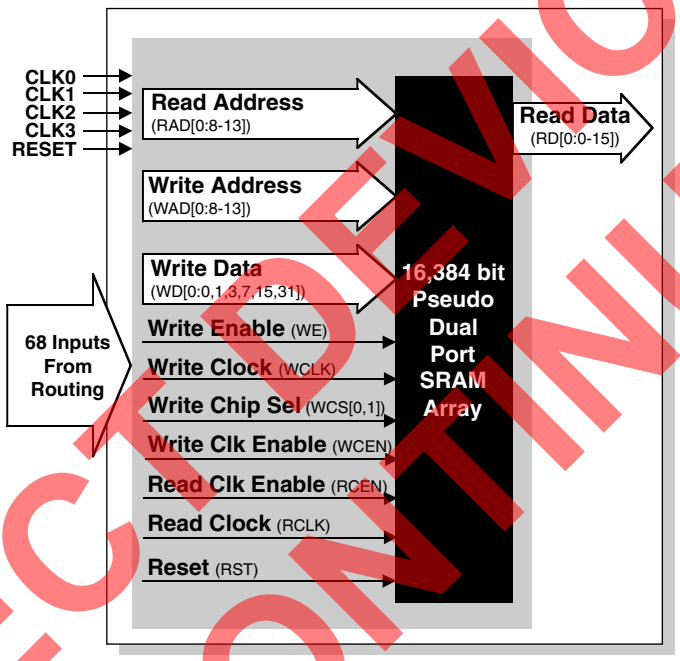


Table 6. Register Clock, Clock Enable, and Reset in Pseudo Dual-Port SRAM Mode

Register	Input	Source
Write Address, Write Data, Write Enable, and Write Chip Select	Clock	WCLK or one of the global clocks (CLK0 - CLK3). The selected signal can be inverted if desired.
	Clock Enable	WCEN or one of the global clocks (CLK1 - CLK2). The selected signal can be inverted if desired.
	Reset	Created by the logical OR of the global reset signal and RST. RST may have inversion if desired.
Read Data and Read Address	Clock	RCLK or one of the global clocks (CLK0 - CLK3). The selected signal can be inverted if desired.
	Clock Enable	RCEN or one of the global clocks (CLK1 - CLK2). The selected signal can be inverted if desired.
	Reset	Created by the logical OR of the global reset signal and RST. RST may have inversion if desired.

Figure 15. PLL Block Diagram

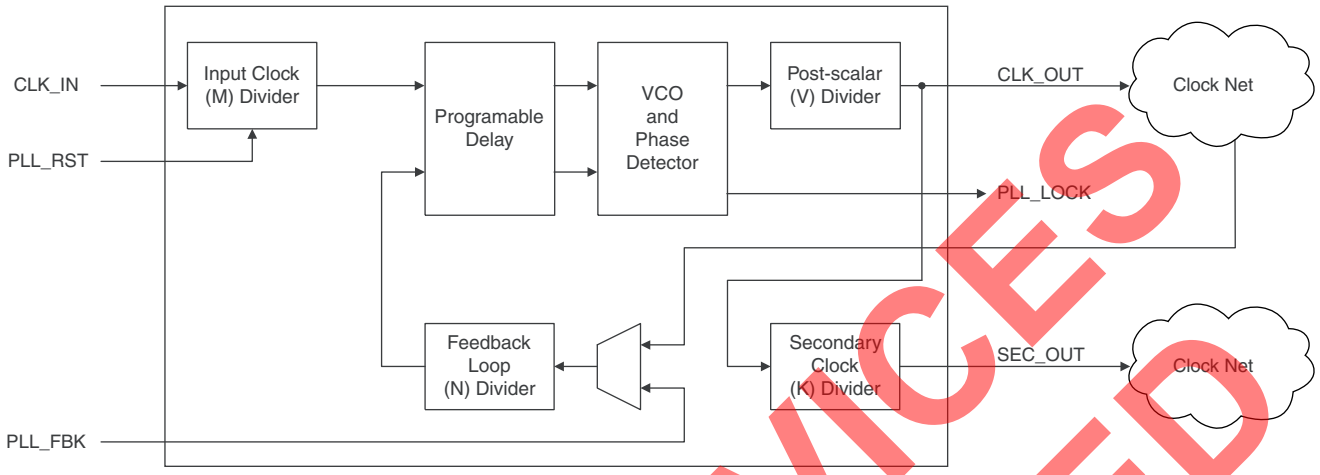
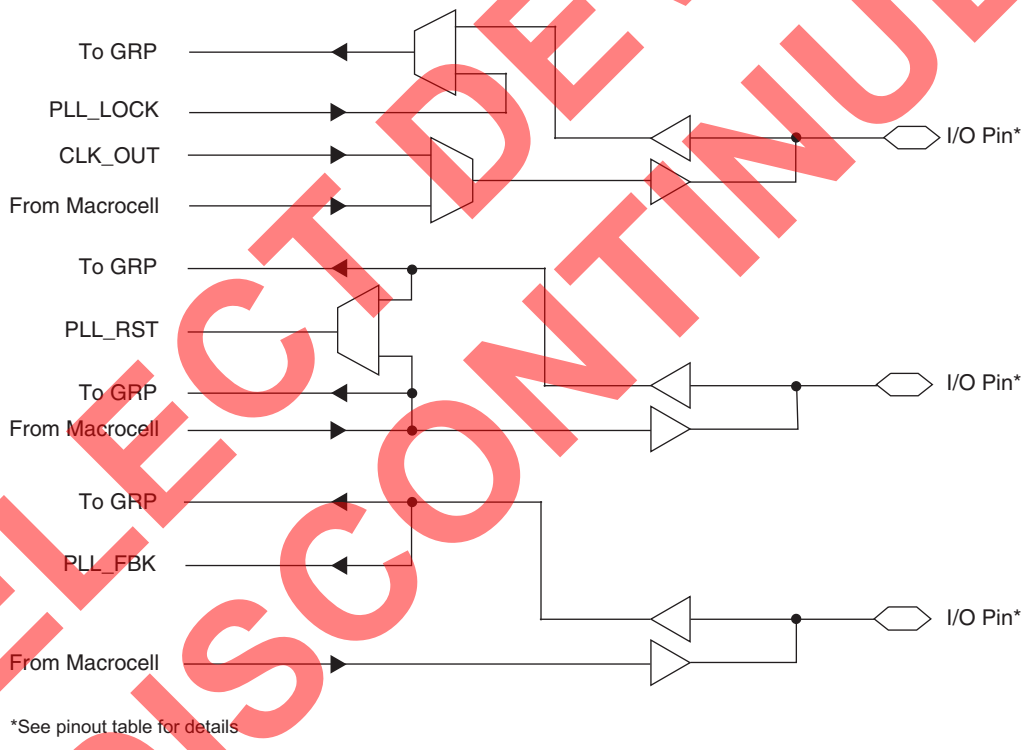


Figure 16. Connection of Optional PLL Inputs and Outputs



In order to facilitate the multiply and divide capabilities of the PLL, each PLL has dividers associated with it: M, N and K. The M divider is used to divide the clock signal, while the N divider is used to multiply the clock signal. The K divider is only used when a secondary clock output is needed. This divider divides the primary clock output and feeds to a separate global clock net. The V divider is used to provide lower frequency output clocks, while maintaining a stable, high frequency output from the PLL's VCO circuit. The PLL also has a delay feature that allows the output clock to be advanced or delayed to improve set-up and clock-to-out times for better performance. For more information on the PLL, please refer to TN1003, sysCLOCK PLL Usage Guide for ispXPGA, ispGDX2, ispXPLD and ispMACH 5000VG Devices.

Figure 17. I/O Cell

Table 10. Shared PTOE Segments

Device	MFBs Associated With Segments
ispXPLD 5256MX	(A, B, C, D) (E, F, G, H)
ispXPLD 5512MX	(A, B, C, D) (E, F, G, H) (I, J, K, L) (M, N, O, P)
ispXPLD 5768MX	(A, B, C, D) (E, F, G, H) (I, J, K, L) (M, N, O, P) (Q, R, S, T) (U, V, W, Z)
ispXPLD 51024MX	(A, B, C, D) (E, F, G, H) (I, J, K, L) (M, N, O, P) (Q, R, S, T) (U, V, W, Z) (Y, Z, AA, AB) (AC, AD, AE, AF)

sysIO Standards

Each I/O within a bank is individually configurable based on the V_{CCO} and V_{REF} settings. Some standards also require the use of an external termination voltage. Table 12 lists the sysIO standards with the typical values for V_{CCO}, V_{REF} and V_{TT}. For more information on the sysIO capability, refer to TN1000, sysIO Usage Guidelines for Lattice Devices.

Table 11. Number of I/Os per Bank

Device	Maximum Number of I/Os per Bank (n)
ispXPLD 5256MX	36
ispXPLD 5512MX	68
ispXPLD 5768MX	96
ispXPLD 51024MX	96

Table 12. ispXPLD 5000MX Supported I/O Standards

sysIO Standard	Nominal V_{CCO}	Nominal V_{REF}	Nominal V_{TT}
LVTTL	3.3V	N/A	N/A
LVCMOS-3.3	3.3V	N/A	N/A
LVCMOS-2.5	2.5V	N/A	N/A
LVCMOS-1.8	1.8V	N/A	N/A
PCI 3.3V	3.3V	N/A	N/A
AGP-1X	3.3V	N/A	N/A
SSTL3, Class I & II	3.3V	1.5V	1.5V
SSTL2, Class I & II	2.5V	1.25V	1.25V
CTT 3.3	3.3V	1.5V	1.5V
CTT 2.5	2.5V	1.25V	1.25V
HSTL, Class I	1.5V	0.75V	0.75V
HSTL, Class III	1.5V	0.9V	0.75V
HSTL, Class IV	1.5V	0.9V	0.75V
GTL+	N/A	1.0V	1.5V
LVPECL, Differential	2.5V, 3.3V	N/A	N/A
LVDS	2.5V, 3.3V	N/A	N/A

Table 13. Differential Interface Standard Support[1]

		sysIO Buffer
LVDS	Driver	Supported
	Receiver	Supported with standard termination
LVPECL	Driver	Supported with external resistor network
	Receiver	Supported with termination

1. For more information, refer to TN1000 – sysIO Usage Guidelines for Lattice Devices.

Control, Clock, sysCONFIG and JTAG Signals

Global clock pins support the same sysIO standards as general purpose I/O. When required the V_{REF} signal is derived from the adjacent bank. When differential standards are supported two adjacent clock pins are paired to form the input. The TOE, PROGRAM, CFG0 and DONE pins of the ispXPLD 5000MX device are the only pins that do not have sysIO capabilities. The JTAG TAP pins support only LVCMOS 3.3, 2.5 and 1.8V standards. The voltage is controlled by V_{CCJ}. These pins only support the LVTTL and LVCMOS standards applicable to the power supply voltage of the device. The global reset global output enable pins are associated with Bank 2 and support all of the sysIO standards.

Hotsocketing

The I/O on the ispXPLD 5000MX devices are well suited for those applications that require hot socketing capability, when configured as LVCMOS or LVTTL. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down device be minimal on active signals.

Programmable Drive Strength

The drive strength of I/Os that are programmed as LVCMOS is tightly controlled and can be programmed to a variety of different values. Thus the impedance an output driver can be closely match to the characteristic impedance of the line it is driving. This allows users to eliminate the need for external series termination resistors.

sysCONFIG Interface

In addition to being able to program the device through the IEEE 1532 interface a microprocessor style interface (sysCONFIG interface) allows reconfiguration of the SRAM bits within the device. For more information on the sysCONFIG capability, refer to TN1026, ispXP Configuration Usage Guidelines.

Security Scheme

A programmable security scheme is provided on the ispXPLD 5000MX devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit prevents readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. The security bit also prevents programming and verification. The entire device must be erased in order to erase the security bit.

Low Power Consumption

The ispXPLD 5000MX devices use zero power non-volatile cells along with full CMOS design to provide low static power consumption. The 1.8V core reduces dynamic power consumption compared with devices with higher core voltages. For information on estimating power consumption, refer to TN1031 Power Estimation in ispXPLD 5000MX Devices.

Density Migration

The ispXPLD 5000MX family has been designed to ensure that different density devices in the same package have compatible pin-outs. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispXPLD 5000MX devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic notes. Internal boundary scan registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for board-level testing. The test access port has its own supply voltage and can operate with LVCMOS3.3, 2.5 and 1.8V standards.

sysIO Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os' physical nature should be minimal so that board test time is minimized. The ispXPLD 5000MX family of devices allows this by offering the user the ability to quickly configure the physical nature of the sysIO cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM™ System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

ispXPLD 5000MX Family External Switching Characteristics [1, 2, 3]

Over Recommended Operating Conditions

Parameter	Description	-4		-45		-5		-52		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{PD}	Data Propagation Delay, 5-PT Bypass	—	4.0	—	4.5	—	5.0	—	5.2	—	7.5	ns
t_{PD_PTSA}	Data propagation delay	—	4.8	—	5.7	—	6.0	—	6.5	—	9.5	ns
t_S	MFB Register Setup Time Before Clock, 5-PT Bypass	2.2	—	2.8	—	2.8	—	3.0	—	4.5	—	ns
t_{S_PTSA}	MFB Register Setup Time Before Clock	2.5	—	3.1	—	3.1	—	3.6	—	5.5	—	ns
t_{SIR}	MFB Register Setup Time Before Clock, Input Register Path	1.0	—	1.0	—	1.0	—	0.5	—	1.7	—	ns
t_H	MFB Register Hold Time Before Clock, 5-PT Bypass	0.0	—	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{H_PTSA}	MFB Register Hold Time Before Clock	0.0	—	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{HIR}	MFB Register Hold Time Before Clock, Input Register Path	0.5	—	0.5	—	0.5	—	1.0	—	1.3	—	ns
t_{CO}	MFB Register Clock-to-Output Delay	—	2.8	—	3.0	—	3.2	—	3.7	—	5.0	ns
t_R	External Reset Pin to Output Delay	—	4.0	—	4.5	—	5.0	—	5.0	—	7.5	ns
t_{RW}	Reset Pulse Duration	1.8	—	1.8	—	1.8	—	2.0	—	3.0	—	ns
$t_{LPTOE/DIS}$	Input to Output Local Product Term Output Enable/Disable	—	6.0	—	7.0	—	7.5	—	8.5	—	10.5	ns
$t_{SPTOE/DIS}$	Input to Output Shared Product Term Output Enable/Disable	—	6.0	—	7.0	—	7.5	—	8.5	—	10.5	ns
$t_{GOE/DIS}$	Global OE Input to Output Enable/Disable	—	4.5	—	5.5	—	5.5	—	6.5	—	7.5	ns
t_{CW}	Clock Width, High or Low	1.5	—	1.5	—	1.5	—	1.8	—	2.5	—	ns
t_{GW}	Gate Width Low (for Low Transparent) or High (for High Transparent)	1.5	—	1.5	—	1.5	—	1.8	—	2.5	—	ns
t_{WIR}	Input Register Clock Width, High or Low	1.5	—	1.5	—	1.5	—	1.8	—	2.5	—	ns
t_{SKEW}	Clock-to-Out Skew, Block Level	—	0.6	—	0.6	—	0.6	—	0.6	—	1.0	ns
f_{MAX} [4]	Clock Frequency with Internal Feedback	—	300	—	275	—	250	—	250	—	150	MHz
f_{MAX} (Ext.)	Clock Frequency with External Feedback, $1/(t_S + t_{CO})$	—	200	—	171	—	166	—	149	—	105	MHz
f_{MAX} (Tog.)	Clock Frequency Max. Toggle	—	333	—	333	—	333	—	277	—	200	MHz
f_{MAX} (CAMC)[5]	Clock Frequency to CAM (Configure Mode)	—	280	—	280	—	230	—	230	—	168	MHz
f_{MAX} (CAM)[5]	Clock Frequency to CAM (Compare Mode)	—	150	—	150	—	150	—	135	—	90	MHz

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
$t_{FIFOWES}$	Write-Enable setup before Write Clock	—	2.33	—	2.33	—	2.91	—	2.91	—	3.03	—	ns
$t_{FIFOWEH}$	Write-Enable hold after Write Clock	—	-2.95	—	-2.95	—	-2.36	—	-2.36	—	-2.27	—	ns
$t_{FIFORES}$	Read-Enable setup before Read Clock	—	2.69	—	2.35	—	2.79	—	2.38	—	4.14	—	ns
$t_{FIFOREH}$	Read-Enable hold after Read Clock	—	-3.17	—	-3.17	—	-2.53	—	-2.53	—	-2.44	—	ns
$t_{FIFORSTO}$	Reset to Output Delay	—	—	3.30	—	3.30	—	4.13	—	4.13	—	4.29	ns
$t_{FIFORSTR}$	Reset Recovery Time	—	1.20	—	1.20	—	1.50	—	1.50	—	1.56	—	ns
$t_{FIFORSTPW}$	Reset Pulse Width	—	0.14	—	0.14	—	0.18	—	0.18	—	0.19	—	ns
$t_{FIFORCLKO}$	Read Clock to FIFO Out Delay	—	—	3.73	—	3.73	—	4.66	—	4.66	—	4.84	ns
CAM – Update Mode													
t_{CAMMSS}	Memory Select Setup before CLK	—	1.40	—	0.70	—	1.50	—	1.40	—	1.44	—	ns
t_{CAMMSH}	Memory Select Hold after CLK	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMENMSKS}$	Enable Mask Register Setup Time before CLK	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{CAMENMSKH}$	Enable Mask Register Setup Time after CLK	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMADDS}$	Address Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{CAMADDH}$	Address Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMDATAS}$	Data Setup Time before Clock	—	-0.41	—	-0.41	—	-0.33	—	-0.33	—	-0.31	—	ns
$t_{CAMDATAH}$	Data Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{CAMDCS}	"Don't Care" Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
t_{CAMDCH}	"Don't Care" Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{CAMRWS}	R/W Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
t_{CAMRWH}	R/W Enable Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{CAMCES}	Clock Enable Setup Time before Clock	—	1.55	—	1.55	—	1.94	—	1.94	—	2.02	—	ns
t_{CAMCEH}	Clock Enable Hold Time after Clock	—	-2.95	—	-2.95	—	-2.36	—	-2.36	—	-2.27	—	ns

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
$t_{CAMWMSKS}$	Write Mask Register Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{CAMWMSKH}$	Write Mask Register Setup Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMRSTO}$	Reset to CAM Output Delay	—	—	3.30	—	3.30	—	4.13	—	4.13	—	4.29	ns
$t_{CAMRSTR}$	Reset Recovery Time	—	1.20	—	1.20	—	1.50	—	1.50	—	1.56	—	ns
$t_{CAMRSTPW}$	Reset Pulse Width	—	0.14	—	0.14	—	0.18	—	0.18	—	0.19	—	ns
CAM – Compare Mode													
$t_{CAMDATAS}$	Data Setup Time before Clock	—	-0.41	—	-0.41	—	-0.33	—	-0.33	—	-0.31	—	ns
$t_{CAMDATAH}$	Data Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMENMSKS}$	Enable Mask Register Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{CAMENMSKH}$	Enable Mask Register Setup Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMCASC}$	CAM Width Expansion Delay	—	—	0.40	—	0.40	—	0.50	—	0.50	—	0.51	ns
t_{CAMCO}	Clock to Output (Address Out) Delay	—	—	6.19	—	6.13	—	6.81	—	6.61	—	9.63	ns
$t_{CAMMATCH}$	Clock to Match Flag Delay	—	—	6.19	—	6.13	—	6.07	—	6.61	—	10.22	ns
$t_{CAMMMATCH}$	Clock to Multi-Match Flag Delay	—	—	5.50	—	5.50	—	6.38	—	6.38	—	7.72	ns
$t_{CAMRSTFLAG}$	CAM Reset to Flags Delay	—	—	3.16	—	3.16	—	3.95	—	3.95	—	4.11	ns
Single Port RAM													
$t_{SPADDDATA}$	Address to Data Delay	—	—	5.97	—	5.97	—	5.97	—	5.97	—	7.76	ns
t_{SPMSS}	Memory Select Setup Before Clock Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{SPMSH}	Memory Select Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{SPCES}	Clock Enable Setup before Clock Time	—	2.30	—	2.30	—	2.30	—	2.30	—	9.80	—	ns
t_{SPCEH}	Clock Enable Hold time after Clock Time	—	-2.95	—	-2.95	—	-2.95	—	-2.95	—	-2.27	—	ns
t_{SPADDS}	Address Setup before Clock Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns

ispXPLD 5000MX Family Timing Adders (Continued)

Parameter	Description	Base Param.	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
LVCMOS_18_8mA_out	Using 1.8V CMOS Standard, 8mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVCMOS_18_12mA_out	Using 1.8V CMOS Standard, 12mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVCMOS_25_4mA_out	Using 2.5V CMOS Standard, 4mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.2	—	1.2	—	1.2	—	1.2	—	1.2	ns
LVCMOS_25_5.33mA_out	Using 2.5V CMOS Standard, 5.33 mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
LVCMOS_25_8mA_out	Using 2.5V CMOS Standard, 8mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.4	—	0.4	—	0.4	—	0.4	—	0.4	ns
LVCMOS_25_12mA_out	Using 2.5V CMOS Standard, 12mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.4	—	0.4	—	0.4	—	0.4	—	0.4	ns
LVCMOS_25_16mA_out	Using 2.5V CMOS Standard, 16mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.4	—	0.4	—	0.4	—	0.4	—	0.4	ns
LVCMOS_33_4mA_out	Using 3.3V CMOS Standard, 4mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.2	—	1.2	—	1.2	—	1.2	—	1.2	ns
LVCMOS_33_5.33mA_out	Using 3.3V CMOS Standard, 5.33mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.2	—	1.2	—	1.2	—	1.2	—	1.2	ns
LVCMOS_33_8mA_out	Using 3.3V CMOS Standard, 8mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.8	—	0.8	—	0.8	—	0.8	—	0.8	ns
LVCMOS_33_12mA_out	Using 3.3V CMOS Standard, 12mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
LVCMOS_33_16mA_out	Using 3.3V CMOS Standard, 16mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
LVCMOS_33_20mA_out	Using 3.3V CMOS Standard, 20mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
AGP_1X_out	Using AGP 1x Standard	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
CTT25_out	Using CTT 2.5V	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
CTT33_out	Using CTT 3.3V	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.2	—	0.2	—	0.2	—	0.2	—	0.2	ns
GTL+_out	Using GTL+	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns

ispXPLD 5000MX Family Timing Adders (Continued)

Parameter	Description	Base Param.	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
HSTL_I_out	Using HSTL 2.5V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
HSTL_III_out	Using HSTL 2.5V, Class III	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
HSTL_IV_out	Using HSTL 2.5V, Class IV	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
LVDS_out	Using Low Voltage Differential Signaling (LVDS)	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.8	—	0.8	—	0.8	—	0.8	—	0.8	ns
LVPECL_out	Using Low Voltage PECL	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
PCI_out	Using PCI Standard	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
SSTL2_I_out	Using SSTL 2.5V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
SSTL2_II_out	Using SSTL 2.5V, Class II	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
SSTL3_I_out	Using SSTL 3.3V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.2	—	0.2	—	0.2	—	0.2	—	0.2	ns
SSTL3_II_out	Using SSTL 3.3V, Class II	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.4	—	0.4	—	0.4	—	0.4	—	0.4	ns

Timing v.1.8

Power Estimation Equations

ICC = ICC_DC + IMFB_CPLD + IMFB_ SRAM/PDPRAM/FIFO + IMFB_DPRAM + IMFB_CAM + IPLL_D

ICC_DC
Use the appropriate value for 5000MC (1.8V power supply) or 5000MV/B (2.5V/3.3V power supply) from the data sheet.

IMFB_CPLD
= ((**K0** * CPLD MFB inputs + **K1** * CPLD Logical Product Terms + **K2** * CPLD GRP from MFB + **K3** * CPLD GRP from IFB) * AF+ **K4**) * FREQ / 1000µA/mA

IMFB_CAM
= CAM Memory MFBs * ((FREQ * **K8**) + **K9**) (CAM operating in typical mode)

IMFB_ SRAM/PDPRAM/FIFO
= (WR_ PERCENT * (**K1** + WR_ PERCENT * 8 * **K0** + **K10** + **K11**) + RD_ PERCENT * (**K1** + 128 * RD_PERCENT * **K0** + 8 * OSW_PERCENT * **K2**)) * SRAM/PDPRAM/FIFO Memory MFBs * FREQ / 1000µA/mA

IMFB_ DPRAM
= (WR_ PERCENT * (2 * **K1** + 2 * WR_ PERCENT * 8 * **K0** + **K10** + **K11**) + RD_ PERCENT * (2 * **K1** + 2 * 128 * RD_PERCENT * **K0** + 8 * OSW_PERCENT * **K2**)) * DPRAM Memory MFBs * FREQ / 1000µA/mA

IPLL_D
= **K5** * PLL_FREQ * number of PLLs used. IPPL_D is the PLL digital component of the VCC supply current.

Analog portion of PLL supply current consumption, from PLL power pin:

IPLL_A = (**K6** * PLL_FREQ + **K7**) * number of PLLs used

Notes:

- ICC = Current consumption of VCC power supply (mA)
- ICC-DC = ICC DC component – Current consumption at 0Mhz (mA)
- IMFB_CPLD = CPLD (non-memory logic) current consumption (mA)
- IMFB_SRAM/PDPRAM/FIFO = Current consumption for SRAM, PDPRAM, and FIFO (mA)
- IMFB_DPRAM = Current consumption for DPRAM (mA)
- IMFB_CAM = Current consumption for CAM (mA)
- IPLL_D = PLL Current consumption of digital VCC power supply (mA)
- IPLL_A = PLL analog power pin current consumption (VCCP pin)

Signal Descriptions

Signal Names	Descriptions
TMS	Input – This pin is the Test Mode Select input, which is used to control the IEEE 1149.1 state machine.
TCK	Input – This pin is the Test Clock input pin, used to clock the IEEE 1149.1 state machine.
TDI	Input – This pin is the IEEE 1149.1 Test Data in pin, used to load data.
TDO	Output – This pin is the IEEE 1149.1 Test Data out pin used to shift data out.
TOE	Input – Test Output Enable pin. TOE tristates all I/O pins when driven low.
GOE0, GOE1	Input – Global output enable inputs.
RESET	Input – This pin resets all the registers in the device. The global polarity for this pin is selectable on a global basis.þ The default is active low. An external pull-down is required when polarity is set to active high.
yzz	Input/Output – These are the general purpose I/O used by the logic array. *y* is the MFB reference (alpha) and z is the macrocell reference (numeric) y: A-X (768 macrocells) y: A-P (512 macrocells) y: A-H (256 macrocells) z: 0-31
GND	GND – Ground
NC	No connect
V_{CC}	V_{CC} – The power supply pins for core logic.
V_{CCO0}, V_{CCO1}, V_{CCO2}, V_{CCO3}	V_{CC} – The power supply pins for I/O banks 0, 1, 2, and 3.
V_{REF0}, V_{REF1}, V_{REF2}, V_{REF3}	Input – This pin defines the reference voltage for I/O banks 0, 1, 2, and 3.
GCLK0, GCLK1, GCLK2, GCLK3	Input – Global clock/clock enable inputs (see Figure 14 for differential pairing).
CLK_OUT0, CLK_OUT1	Output – Optional clock output from PLL 0 and 1.
PLL_RST0, PLL_RST1	Input – Optional input resets the M divider in PLL 0 and 1.
PLL_FBK0, PLL_FBK1	Input – Optional feedback input for PLL 0 and 1.
GNDP	GND – Ground for PLLs.
V_{CCP}	V_{CC} – The power supply pin for PLLs.
V_{CCJ}	V_{CC} – The power supply for the IEEE 1149.1 interface.
DATA*x*	I/O – sysCONFIG data pins, bit *x*.
CSB	Input – sysCONFIG interface chip select. Drive low to select sysCONFIG interface.
CFG0	Input – Defines SRAM configuration mode. Low: sysCONFIG port, high: E^2CMOS or IEEE 1149.1 TAP.
PROGRAMB	Input – Controls the programming of SRAM. Hold high for normal operation. Toggle low to reload SRAM from E^2 memory.
CCLK[1]	Input – Clock for sysCONFIG interface. Reads and writes occur on the rising edge of the clock.
READ[1]	Input – Drive high to perform reads from the sysCONFIG interface.
INITB	I/O – Indicates status of configuration. Can be driven low to inhibit configuration.
DONE	Output (open drain) – Indicates status of configuration.

1. These inputs should not toggle during power up for proper power-up configuration.

ispXPLD 5512MX Logic Signal Connections

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
0	109N	O30	O11	P18	O31	208	C4	B4
0	109P	O28	O10	P16	O29	1	E4	A4
0	110N	O26	M17	O17	O27	2	B1	B3
0	110P	O24	M16	O16	O25	3	C1	A3
0	111N	O22	M15	O15	O23	4	D3	F5
—	—	V_{CCO0}	—	—	—	5	V_{CCO0}	V_{CCO0}
0	111P	O20	M14	O14	O21	6	C2	G6
—	—	GND (Bank 0)	—	—	—	7	GND (Bank 0)	GND (Bank 0)
0	112N	O18	M13	O13	O19	8	E3	H6
0	112P	O16	M12	O12	O17	9	D2	G5
0	113N	O14	O9	P14	O15	—	—	D3
0	113P	O12	O8	P12	O13	—	—	D2
0	114N	O10	O7	P10	O11	—	—	E4
0	114P	O8	O6	P8	O9	—	—	E3
0	115N	O6	O5	P6	O7	—	—	F4
0	115P	O4	O4	P4	O5	—	—	G4
0	116N	O2	O3	P2	O3	—	—	C2
—	—	V_{CCO0}	—	—	—	—	V_{CCO0}	V_{CCO0}
0	116P	O0	O2	P0	O1	—	—	C1
—	—	GND (Bank 0)	—	—	—	—	GND (Bank 0)	GND (Bank 0)
0	117N	P30	O1	—	P31	—	D1	F3
0	117P	P28	O0	—	P29	—	E1	G3
0	118N	P26	O31	—	P27	—	F4	H4
—	—	V_{CC}	—	—	—	10	V_{CC}	V_{CC}
0	118P	P24	O30	—	P25	—	F5	J4
0	119N	P22	M11	O11	P23	11	E2	H5
0	119P	P20/CLK_OUT0	M10	O10	P21	12	F2	J5
0	120N	P18	M9	O9	P19	13	F1	E2
0	120P	P16	M8	O8	P17	14	G1	F2
—	—	GND	—	—	—	15	GND	GND
0	121N	P14	M7	O7	P15	16	F3	D1
—	—	V_{CCO0}	—	—	—	17	V_{CCO0}	V_{CCO0}
0	121P	P12	M6	O6	P13	18	G5	E1
—	—	GND (Bank 0)	—	—	—	19	GND (Bank 0)	GND (Bank 0)
0	122N	P10	M5	O5	P11	20	H5	J3
0	122P	P8/PLL_RST0	M4	O4	P9	21	G4	H2
0	123N	P6	—	—	P7	22	G3	G2
0	123P	P4/PLL_FBK0	—	—	P5	23	H3	G1
0	124N	P2	—	—	P3	24	G2	H1
0	124P	P0	—	—	P1	25	H1	J1
—	GCLK0P	GCLK0	—	—	—	26	H2	N7
—	—	V_{CCJ}	—	—	—	See Power Supply and NC Connections Table		

ispXPLD 5512MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
3	61N	I14	I23	K23	I15	149	G13	D22
3	61P	I12	I22	K22	I13	150	G12	D21
3	62N	I10	I21	K21	I11	151	F14	J20
3	62P	I8/CLK_OUT1	I20	K20	I9	152	E15	J19
3	63N	I6	K31	—	I7	—	F12	E20
—	—	V_{CC}	—	—	—	153	VCC	VCC
3	63P	I4	K30	L30	I5	—	F13	F20
3	64N	I2	K29	L28	I3	—	D16	H17
3	64P	I0	K28	L26	I1	—	D15	H18
—	—	GND (Bank 3)	—	—	—	—	GND (Bank 3)	GND (Bank 3)
3	65N	J30	K27	—	J31	—	—	J18
—	—	V_{CCO3}	—	—	—	—	V_{CCO3}	V_{CCO3}
3	65P	J28	K26	—	J29	—	—	H19
3	66N	J26	K25	—	J27	—	—	G20
3	66P	J24	K24	—	J25	—	—	G19
3	67N	J22	K23	—	J23	—	—	C22
3	67P	J20	K22	—	J21	—	—	C21
3	68N	J18	K21	—	J19	—	—	D20
3	68P	J16	K20	—	J17	—	—	C19
3	69N	J14	K19	—	J15	—	C16	F19
3	69P	J12	K18	—	J13	—	B16	E19
—	—	GND (Bank 3)	—	—	—	—	GND (Bank 3)	GND (Bank 3)
3	70N	J10	K17	—	J11	—	C15	G18
—	—	V_{CCO3}	—	—	—	—	V_{CCO3}	V_{CCO3}
3	70P	J8	K16	—	J9	—	B15	F18
3	71N	J6	K15	—	J7	—	E14	B20
3	71P	J4	K14	—	J5	—	D14	B19
3	72N	J2	K13	—	J3	—	E13	A20
3	72P	J0	K12	—	J1	—	A15	A19
3	73N	K30	I19	K19	K31	154	D12	D18
3	73P	K28	I18	K18	K29	155	B14	C18
3	74N	K26	I17	K17	K27	156	C13	G17
3	74P	K24	I16	K16	K25	157	A14	F16
3	75N	K22	I31	K31	K23	158	A13	E17
3	75P	K21	I30	K30	—	159	B13	D17
—	—	GND (Bank 3)	—	—	—	160	GND (Bank 3)	GND (Bank 3)
3	76N	K20	K11	L21	—	—	D11	B18
—	—	V_{CCO3}	—	—	—	161	V_{CCO3}	V_{CCO3}
3	76P	K18	K10	L20	K19	—	B12	A18
3	77N	K16	K9	L18	K17	—	C12	C17
3	77P	K14	K8	L16	K15	—	E11	B17
3	78N	K12	K7	L12	K13	—	—	C16
3	78P	K10	K6	L10	K11	—	—	B16

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	TCK	-	-	-	J6	T1
-	-	TDO	-	-	-	K2	V1
1	0P	A30/DATA0	C0	A0	A31	K3	W1
1	0N	A28/DATA1	C1	A1	A29	J3	Y1
1	1P	A26/DATA2	C2	A2	A27	J5	P3
1	1N	A24/DATA3	C3	A3	A25	J4	R3
1	2P	A22/DATA4	C4	A4	A23	L2	T2
1	2N	A20/DATA5	C5	A5	A21	M1	U2
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	3P	A18/DATA6	C6	A6	A19	K4	V2
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	3N	A16/DATA7	C7	A7	A17	L3	W2
-	-	GND	-	-	-	GND	GND
1	4P	A14/INITB	C8	A8	A15	K5	R4
1	4N	A12/CSB	C9	A9	A13	L5	T4
1	5P	A10/READ	C10	A10	A11	N1	R6
1	5N	A8/CCLK	C11	A11	A9	M2	R5
1	6P	A6	-	-	A7	—	U3
-	-	VCC	-	-	-	VCC	VCC
1	6N	A4	-	-	A5	P1	V3
1	7P	A2	-	-	A3	M3	Y2
1	7N	A0	-	-	A1	L4	W3
1	8P	B30	D0	-	B31	N2	U5
1	8N	B28	D2	-	B29	P2	T5
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	9P	B26	D4	-	B27	R1	U4
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	9N	B24	D6	-	B25	R2	V4
1	10P	B22	D8	-	B23	T2	AA3
1	10N	B20	D10	-	B21	T3	AB3
1	-	B18	D12	-	B19	—	Y4
-	-	DONE	-	-	-	M4	AA4
1	11P	B14	-	-	B15	—	AB2
1	11N	B12	-	-	B13	—	U6
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	12P	B10	-	-	B11	—	V5
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	12N	B8	-	-	B9	—	W6
1	13P	B6	C12	A12	B7	N3	AB4
1	13N	B4	C13	A13	B5	P4	AB5
1	14P	B2	C14	A14	B3	N5	T6
1	14N	B0	C15	A15	B1	M6	U7
-	-	PROGRAMB	-	-	-	R3	W5

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
3	126N	W4	V11	U21	W5	B18	E19
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	126P	W6	V10	U20	W7	A18	E18
-	-	GND	-	-	-	GND	GND
3	127N	W8	V9	U18	W9	C17	C24
-	-	VCC	-	-	-	VCC	VCC
3	127P	W10	V8	U16	W11	B17	C23
3	128N	W12	V7	U12	W13	C16	D22
3	128P	W14	V6	U10	W15	B16	D21
3	129N	W16	V5	U8	W17	F13	E21
3	129P	W18	V4	U6	W19	F15	D20
3	130N	W20	V3	U5	W21	D16	D19
3	130P	W22	V2	U4	W23	E16	D18
3	131N	W24	V1	U2	W25	A16	C22
3	131P	W26	V0	U0	W27	A15	C21
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	132N	W28	X15	V15	W29	B15	C20
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	132P	W30	X14	V14	W31	A14	C19
3	133N	X0	X13	V13	X1	D15	C18
3	133P	X2	X12	V12	X3	E15	C17
3	134N	X4	X11	V11	X5	D14	B24
3	134P	X6	X10	V10	X7	F14	B23
3	135N	X8	X9	V9	X9	A13	B22
3	135P	X10	X8	V8	X11	B13	B21
3	136N	X12/VREF3	X29	V29	X13	C14	B20
3	136P	X14	X28	V28	X15	E14	B19
3	137N	X16	X7	V7	X17	E13	B18
3	137P	X18	X6	V6	X19	F12	B17
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	138N	X20	X5	V5	X21	D13	A24
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	138P	X22	X4	V4	X23	C13	A23
3	139N	X24	X3	V3	X25	E12	A22
-	-	GND	-	-	-	GND	GND
3	139P	X26	X2	V2	X27	C12	A21
-	-	VCC	-	-	-	VCC	VCC
3	140N	X28	X1	V1	X29	B12	A20
3	140P	X30	X0	V0	X31	A12	A19
0	141N	Y30	Y31	AA31	Y31	E11	A18
-	-	VCC	-	-	-	VCC	VCC
0	141P	Y28	Y30	AA30	Y29	C11	A17
-	-	GND	-	-	-	GND	GND

Global Clock LVDS pair options: GCLK0 and GCLK1, as well as GCLK2 and GCLK3, can be paired together to receive differential clocks; where GCLK0 and GCLK3 are the positive LVDS inputs.